IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Akira MATSUDA et al. Group Art Unit: 1775

Serial No.: 10/719,020 Examiner: Robert R. Koehler

Filed: November 24, 2003 Confirmation Number: 9168

For: PLATING BATH FOR FORMING THIN RESISTANCE LAYER,

METHOD OF FORMATION OF RESISTANCE LAYER, CONDUCTIVE BASE WITH RESISTANCE LAYER, AND CIRCUIT BOARD MATERIAL WITH RESISTANCE LAYER

> Attorney Docket Number: 032130 Customer Number: 38834

RESPONSE

Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450 Date: July 5, 2005

Sir:

In response to the Office Action dated March 4, 2005, the response due date extended to July 4, 2005 by a 1-month Extension of Time, please amend the above-identified application as follows:

<u>Amendments to the Claims</u> are reflected in the listing of claims that begins on page 2 of this paper.

Remarks begin on page 6 of this paper.